Description

Title of Invention: Wafer polishing method and wafer polishing device

[CROSS REFERENCE TO RELATED APPLICATIONS]

[0001] The present application claims priority from Japanese Patent Application No. 2020-151460, filed on September 9, 2020, the entire disclosure of which is particularly incorporated herein.

[Technical Field]

[0002] The present invention relates to a wafer polishing method and a wafer polishing device.

[Background Art]

[0003] The devices for polishing the surface of a wafer includes a one side polishing device for polishing one side of a wafer, and a double side polishing device for polishing both sides of a wafer. With the one side polishing device, normally, with the surface to be polished of a wafer held on a polishing head pressed against a polishing pad bonded on a surface plate, the polishing head and the surface plate are respectively rotated, thereby bringing the surface to be polished of the wafer and the polishing pad into contact with each other. By supplying an abrasive to between the surface to be polished and the polishing pad thus brought into contact with each other, it is possible to polish the surface to be polished of the wafer (for example, see Japanese Patent Application Publication No. 2006-2663903 (the entire description of which is herein referred to as reference)).

[Summary of Invention]

[0004] With wafer polishing using a one side polishing device, as described in paragraph 0007 of Japanese Patent Application Publication No. 2006-2663903, or the like, in order to perform polishing processing with stability, a retainer ring is provided to hold a wafer to be polished. However, in order to improve the stability of polishing processing in wafer polishing, only provision of a retainer ring is not sufficient, and proper setting of the polishing conditions can contribute to the improvement of the stability of polishing processing in wafer polishing. However, conventionally, there has been no choice but to repeat much trial and error in order to find such polishing conditions.

[0005] In accordance with one aspect of the present invention, it is an object to enable stable wafer polishing processing to be performed by readily setting proper polishing conditions.